

MODEL NO: 17-21UYC/S530-A3/TR8

Device Number: DSE -171-071 REV. 1.0

0805 Package Chip LEDs

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Features:

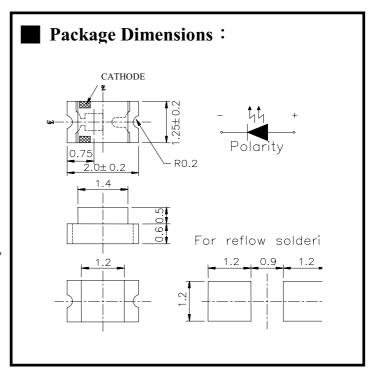
- Package in 8mm tape on 7" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase refold solder process.
- Mono-color type.

Descriptions:

- · The 17-21 SMD Taping is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- · Besides, light weight makes them ideal for miniature applications, etc.

Applications:

- · Automotive: backlighting in dashboard and switch.
- · Telecommuncation: indicator and backlighting in telephone and fax.
- · Flat backlight for LCD, switch and symbol.
- · General use.



Notes:

Tolerances Unless Dimension ± 0.1mm Angle± 0.5°

Unit=mm

| PART NO | Chip | | Lens Color |
|----------------------|----------|---------------|-------------|
| | Material | Emitted Color | Lens Color |
| 17-21UYC/S530-A3/TR8 | AlGaInP | Super Yellow | Water Clear |

Office: NO. 25, Lane 76, Sec.3, Chung Yang Rd., Tucheng 236, Taipei, Taiwan, R.O.C.

TEL: 886-2-2267-2000, 2267-9936

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http://www.everlight.com

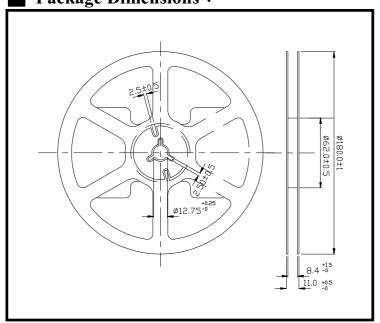


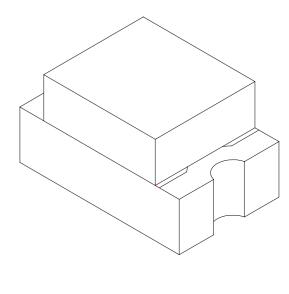
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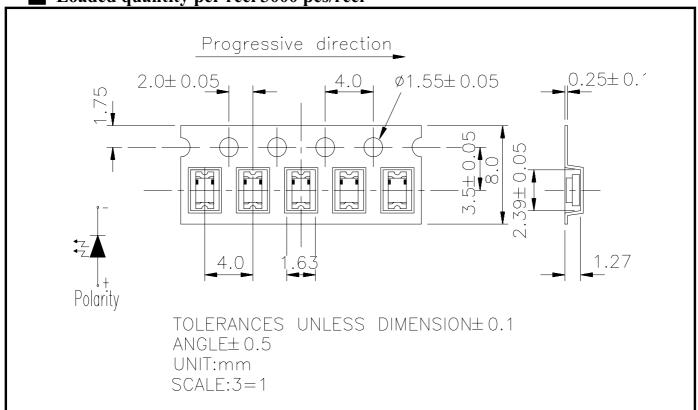
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Package Dimensions:





Loaded quantity per reel 3000 pcs/reel:





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Absolute Maximum Ratings at $Ta = 25^{\circ}C$

| Parameter | Symbol | Rating | Unit |
|--|----------|--------------------|-------------------------|
| Reverse Voltage | V_R | Vr 5 | |
| Forward Current | IF | 25 | mA |
| Operating Temperature | Topr | -40 ~ +85 | $^{\circ}\!\mathbb{C}$ |
| Storage Temperature | Tstg | -40 ~ +90 | $^{\circ}\! \mathbb{C}$ |
| Soldering Temperature | Tsol | 260 (for 5 second) | $^{\circ}\! \mathbb{C}$ |
| Electrostatic Discharge | ESD | 2000 | V |
| Power Dissipation | Pd | 60 | mW |
| Peak Forward Current(Duty 1/10 @ 1KHZ) | Ir(Peak) | 160 | mA |

Electronic Optical Characteristics:

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Condition |
|---------------------------------|---------|------|------|------|------|----------------------|
| Luminous Intensity | Iv | | 4 | | mcd | I _F =2mA |
| | | 41 | 64 | | mcd | I _F =20mA |
| Viewing Angle | 2 0 1/2 | | 140 | | deg | I _F =20mA |
| Peak Wavelength | λр | | 591 | | nm | I _F =20mA |
| Dominant Wavelength | λd | | 589 | | nm | I _F =20mA |
| Spectrum Radiation Bandwidth | Δλ | | 15 | | nm | I _F =20mA |
| Forward Voltage | VF | | 2.0 | 2.4 | V | I _F =20mA |
| Reverse Current | Ir | | | 10 | μΑ | $V_R=5V$ |



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Reliability Test Items And Conditions

| NO | Item | Test Conditions | Test Hours/Cycle | Sample Size | Ac/Re |
|----|-------------------------------------|---|---------------------|----------------|-------|
| 1 | Solder Heat | TEMP : 260°C ± 5 °C | 5 SEC | 76 PCS | 0/1 |
| 2 | Temperature Cycle | H: +85°C 30min ∫ 5 min L: -55°C 30min | 50 CYCLES | 76 PCS | 0/1 |
| 3 | Thermal Shock | H: +100°C 5min $ ∫ 10 sec. $ L: -10°C 5min. | 50 CYCLES | 76 PCS | 0/1 |
| 4 | High Temperature Storage | TEMP : 100°C | 1000 HR. | 76 PCS | 0/1 |
| 5 | Low Temperature Storage | TEMP : -55°℃ | 1000 HR. | 76 PCS | 0/1 |
| 6 | DC Operating Life | I _F = 20 mA | 1000 HR. | 76 PCS | 0/1 |
| 7 | High Temperature / High Humidity | 85°C/85% RH | 1000 HR. | 76 PCS | 0/1 |

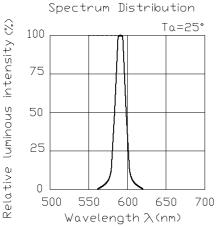


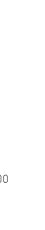
MODEL NO: Device Number: DSE -171-071 REV. 1.0 17-21UYC/S530-A3/TR8

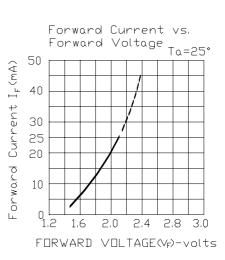
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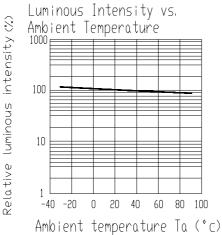
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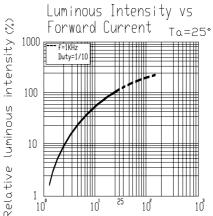
Typical Electro-Optical Characteristic Curves

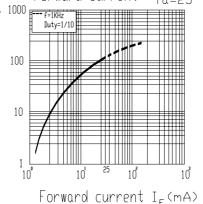


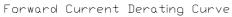


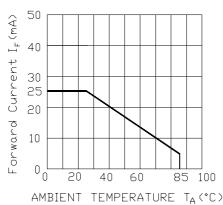


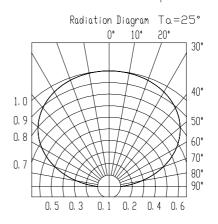












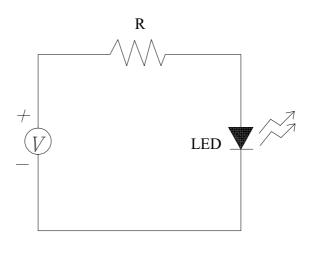


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Test Circuit



Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

- 2. Storage time
 - 2.1 The operation of temperature and R.H. are : 5° C ~ 35° C, R.H. 60° M.
 - 2.2 Once the package is opened, the products should be used within a week. Otherwise, they should be ketp in a damp proof box with desiccanting agent. Considering the tape life, we suggest our customers to use our products within a year(from production date).
 - 2.3 If opened more than one week in an atmosphere $5^{\circ}\text{C} \sim 35^{\circ}\text{C}$, R.H.60%, they should be treated at $60^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 15hrs.
 - 2.4 When you discover that the desiccant in the package has a pink color (Normal=blue), you should treat them in the same conditions as 2.3.



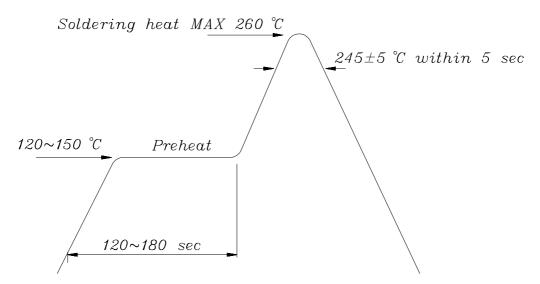
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Soldering heat reliability (DIP)

Please refer to the following figure:

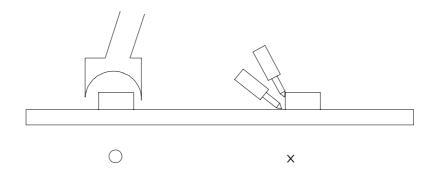


Soldering Iron

Basic spec is ≤ 5 sec. when 260°C. If temperature is higher, time should be shorter (+10°C \rightarrow -1sec.). Power dissipation of iron should be smaller than 15 W, and temperature should be controllable. Surface temperature of the device should be under 230 °C.

Rework

- 1. Customer must finish rework within 5 sec. under 260° C.
- 2. Copper foil can not be touched by the head of iron.
- 3. Twin-head type is preferred.





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■ Reflow Temp / Time:

